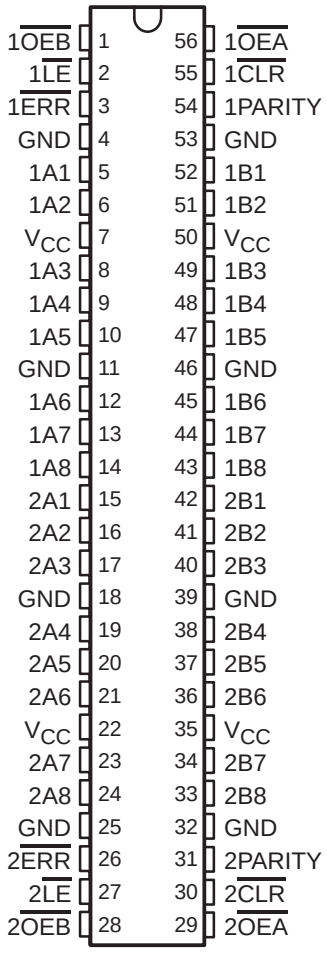
SCBS153B – OCTOBER 1992 – REVISED JANUARY 1997

- **Members of the Texas Instruments *Widebus*™ Family**
- **State-of-the-Art *EPIC*-II*B*™ BiCMOS Design Significantly Reduces Power Dissipation**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Parity-Error Flag With Parity Generator/Checker**
- **Latch for Storage of the Parity-Error Flag**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

SN54ABT16853 . . . WD PACKAGE
SN74ABT16853 . . . DGG OR DL PACKAGE
(TOP VIEW)



description

The ’ABT16853 dual 8-bit to 9-bit parity transceivers are designed for communication between data buses. When data is transmitted from the A bus to the B bus, a parity bit is generated. When data is transmitted from the B bus to the A bus, with its corresponding parity bit, the open-collector parity-error ($\overline{ERR}$) output indicates whether or not an error in the B data has occurred. The output-enable ($\overline{OEA}$ and $\overline{OEB}$) inputs can be used to disable the device so that the buses are effectively isolated. The ’ABT16853 provide true data at the outputs.

A 9-bit parity generator/checker generates a parity-odd (PARITY) output and monitors the parity of the I/O ports with the $\overline{ERR}$ flag. The parity-error output can be passed, sampled, stored, or cleared from the latch using the latch-enable ($\overline{LE}$) and clear ($\overline{CLR}$) control inputs. When both $\overline{OEA}$ and $\overline{OEB}$ are low, data is transferred from the A bus to the B bus, and inverted parity is generated. Inverted parity is a forced error condition that gives the designer more system diagnostic capability.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

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description (continued)

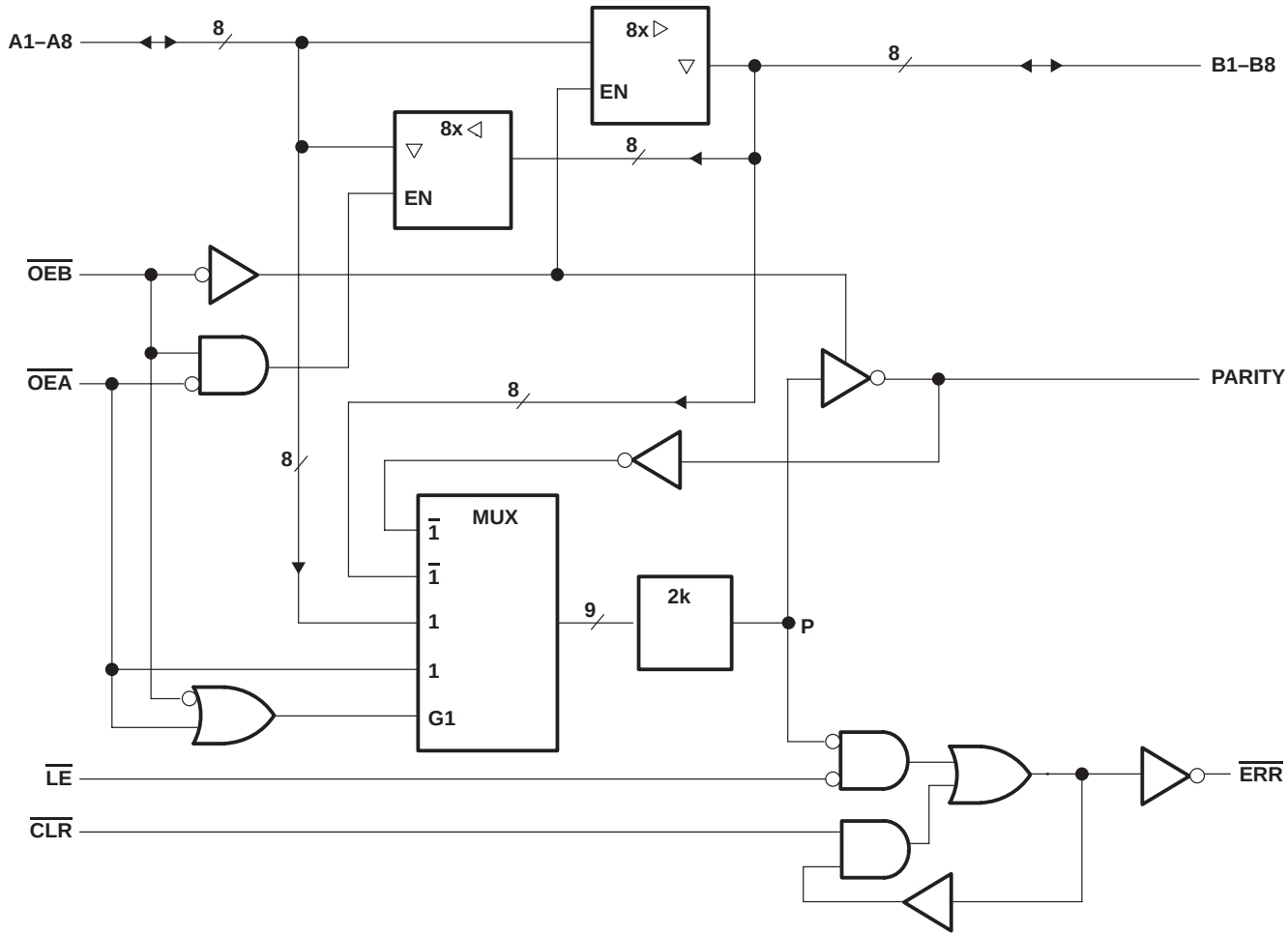
The SN54ABT16853 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16853 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE

INPUTS						OUTPUT AND I/O				FUNCTION
$\overline{OEB}$	$\overline{OEA}$	$\overline{CLR}$	LE	AI Σ OF H	BI† Σ OF H	A	B	PARITY	$\overline{ERR}$‡	
L	H	X	X	Odd	NA	NA	A	L	NA	A data to B bus and generate parity
				Even				H		
H	L	X	L	NA	Odd	B	NA	NA	H	B data to A bus and check parity
					Even				L	
H	L	H	H	NA	X	X	NA	NA	NC	Store error flag
X	X	L	H	X	X	X	NA	NA	H	Clear error-flag register
H	H	H	H	X	X	Z	Z	Z	NC	Isolation§ (parity check)
		L	H	X					H	
		X	L	L Odd					H	
		X	L	H Even					L	
L	L	X	X	Odd	NA	NA	A	H	NA	A data to B bus and generate inverted parity
				Even				L		

NA = not applicable, NC = no change, X = don't care
† Summation of high-level inputs includes PARITY along with Bi inputs.
‡ Output states shown assume $\overline{ERR}$ was previously high.
§ In this mode, $\overline{ERR}$ (when clocked) shows inverted parity of the A bus.

logic diagram (each transceiver) (positive logic)

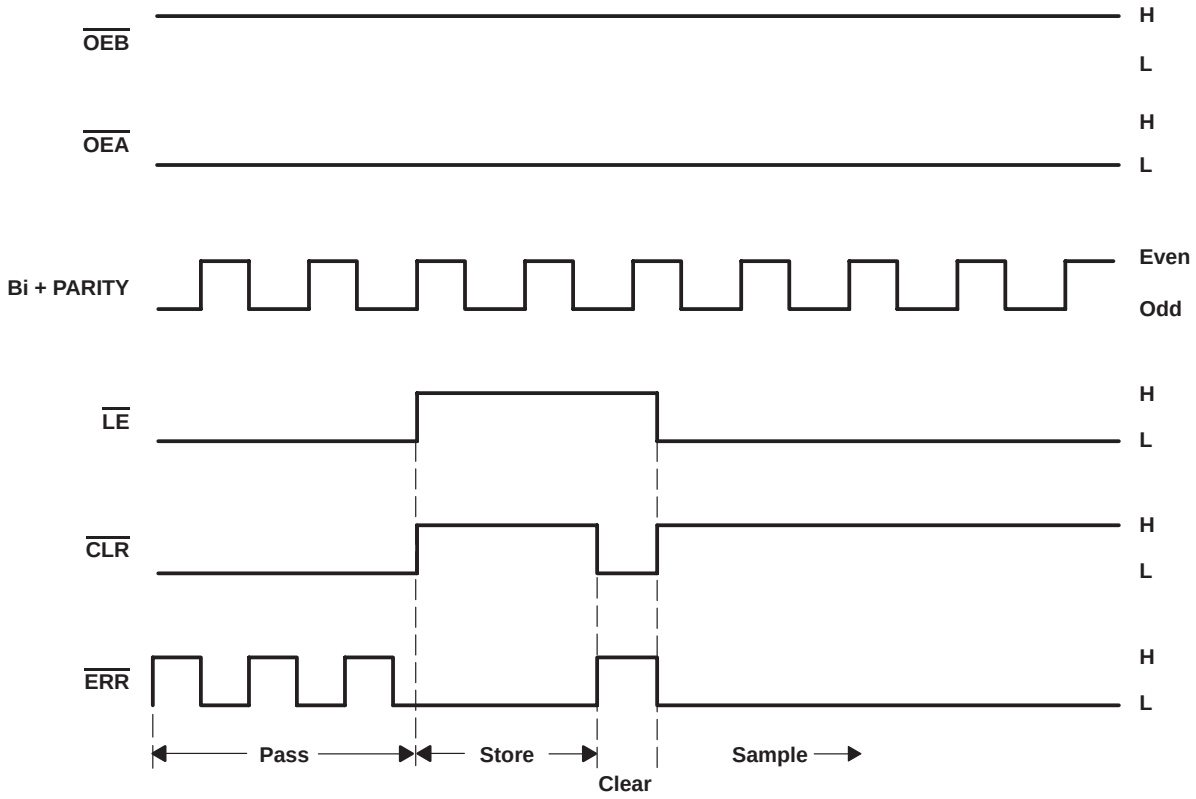


ERROR-FLAG FUNCTION TABLE

INPUTS		INTERNAL TO DEVICE	OUTPUT	OUTPUT	FUNCTION
$\overline{CLR}$	$\overline{LE}$	POINT P	$\overline{ERR}_{n-1}$†	$\overline{ERR}$	
L	L	L	X	L	Pass
		H		H	
H	L	L	X	L	Sample
		X	L	L	
		H	H	H	
L	H	X	X	H	Clear
H	H	X	L	L	Store
			H	H	

† State of $\overline{ERR}$ before changes at $\overline{CLR}$, $\overline{LE}$, or point P

error-flag waveforms



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . . –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) . . . . . –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O . . . . . –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT16853 . . . . . 96 mA
SN74ABT16853 . . . . . 128 mA
Input clamp current, I_{IK} ($V_I < 0$) . . . . . –18 mA
Output clamp current, I_{OK} ($V_O < 0$) . . . . . –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package . . . . . 81°C/W
DL package . . . . . 74°C/W
Storage temperature range, T_{stg} . . . . . –65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

recommended operating conditions (see Note 3)

			SN54ABT16853		SN74ABT16853		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
V_{OH}	High-level output voltage	$\overline{ERR}$		5.5		5.5	V
I_{OH}	High-level output current	Except $\overline{ERR}$		–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT16853		SN74ABT16853		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}	All outputs except $\overline{ERR}$	V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5	3		2.5				V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3	3.4		3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA				2				
			I_{OH} = –32 mA	2*	2.7				2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 24 mA		0.25	0.55		0.55			V
			I_{OL} = 64 mA		0.3	0.55*				0.55	
V_{hys}					100						mV
I_{OH}	$\overline{ERR}$	V_{CC} = 4.5 V,	V_{OH} = 5.5 V			20		20		20	µA
I_{off}		V_{CC} = 0,	V_I or $V_O \le$ 4.5 V			±100				±100	µA
I_{CEX}	Outputs high	V_{CC} = 5.5 V,	V_O = 5.5 V			50		50		50	µA
I_I	Control inputs	V_{CC} = 5.5 V, V_I = V_{CC} or GND				±1		±1		±1	µA
	A or B ports					±100		±100		±100	
I_{IL}	A or B ports	V_{CC} = 0,	V_I = GND			–50		–50		–50	µA
I_O‡		V_{CC} = 5.5 V,	V_O = 2.5 V	–50	–100	–180	–50	–180	–50	–180	mA
I_{OZH}§		V_{CC} =5.5 V,	V_O = 2.7 V			50		50		50	µA
I_{OZL}§		V_{CC} = 5.5 V,	V_O = 0.5 V			–50		–50		–50	µA
I_{CC}	A or B ports	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high		1.5	2		2		2	mA
			Outputs low		32	40		40		40	
			Outputs disabled		1	2		2		2	
ΔI_{CC}¶		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				50		50		50	µA
C_i	Control inputs	V_I = 2.5 V or 0.5 V			3						pF
C_{io}	A or B ports	V_O = 2.5 V or 0.5 V			9						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
§ The parameters I_{OZH} and I_{OZL} include the input leakage current.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

PRODUCT PREVIEW

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timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			V_{CC} = 5 V, T_A = 25°C		SN54ABT16853		SN74ABT16853		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration	$\overline{LE}$ high or low	8.5		8.5		8.5		ns
		$\overline{CLR}$ low	4		4		4		
t_{su}	Setup time	A, B, and PARITY before $\overline{LE}\downarrow$	10		10		10		ns
		$\overline{CLR}$ before $\overline{LE}\downarrow$	0		0		0		
t_h	Hold time	A, B, and PARITY after $\overline{LE}\downarrow$	0		0		0		ns
		$\overline{CLR}$ after $\overline{LE}\downarrow$	0		0		0		

PRODUCT PREVIEW

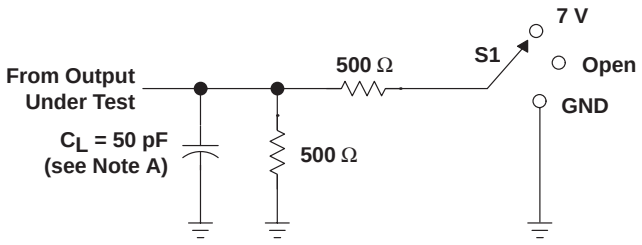
switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			SN54ABT16853		SN74ABT16853		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	1.5	2.5	3.3	1.5	4.2	1.5	4.1	ns
t_{PHL}			2	3.1	3.9	2	4.5	2	4.3	
t_{PLH}	A or $\overline{OE}$	PARITY	2	4.6	5.9	2	7.3	2	7.1	ns
t_{PHL}			2	4.8	6.2	2	7.6	2	7.2	
t_{PLH}	$\overline{CLR}$	$\overline{ERR}$	2	3.7	5.1	2	5.9	2	5.7	ns
t_{PZH}	$\overline{OE}$	A or B	2	3.9	4.9	2	5.8	2	5.6	ns
t_{PZL}			2.5	4.3	5.1	2.5	6.2	2.5	6	
t_{PHZ}	$\overline{OE}$	A or B	2	3.6	4.5	2	5.5	2	5.4	ns
t_{PLZ}			1.5	3	3.8	1.5	4.7	1.5	4.3	
t_{PZH}	$\overline{OE}$	PARITY	2	3.6	5	2	5.8	2	5.7	ns
t_{PZL}			2.5	4.4	5.8	2.5	6.7	2.5	6.5	
t_{PHZ}	$\overline{OE}$	PARITY	1.5	3.2	4	1.5	4.8	1.5	4.7	ns
t_{PLZ}			1.5	2.9	3.7	1.5	4.2	1.5	4.1	
t_{PLH}	$\overline{LE}$	$\overline{ERR}$	2	3.5	4.2	2	5	2	4.8	ns
t_{PHL}			2	3.4	4.4	2	5.2	2	4.9	
t_{PLH}	A, B, or PARITY	$\overline{ERR}$	2	4.5	6.3	2	7.5	2	7.2	ns
t_{PHL}			2	4.8	6.3	2	7.7	2	7.4	

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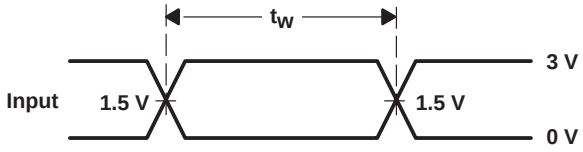
PARAMETER MEASUREMENT INFORMATION



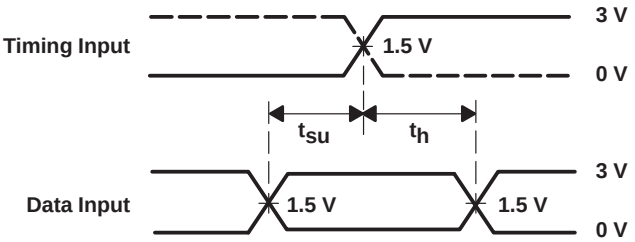
LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open

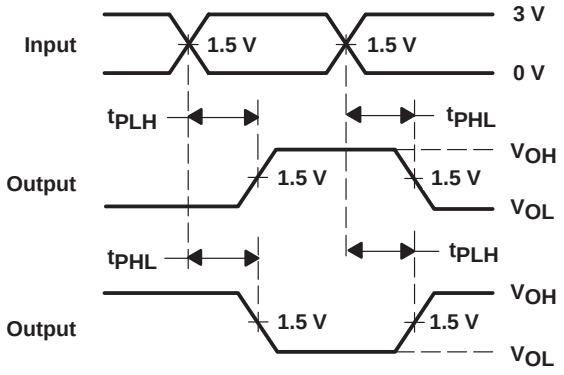
$\overline{ERR}$	S1
t_{PHL} (see Note E)	7 V
t_{PLH} (see Note F)	7 V



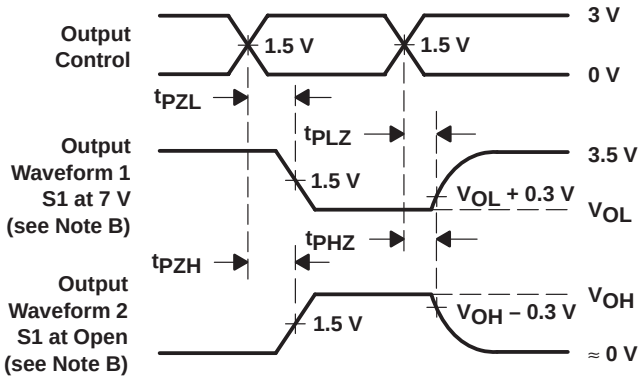
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.
E. t_{PHL} is measured at 1.5 V.
F. t_{PLH} is measured at V_{OL} + 0.3 V.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
74ABT16853DGGRE4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ABT16853DGGRG4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16853DGGR	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16853DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16853DLG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16853DLR	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16853DLRG4	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:
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NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

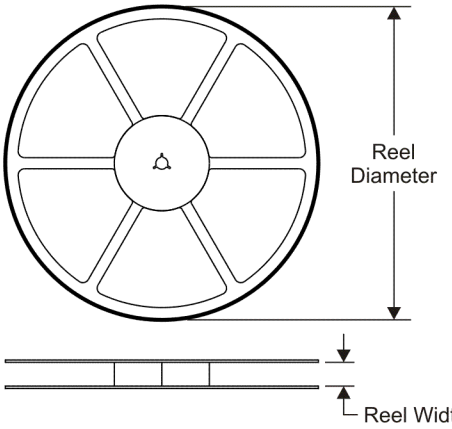
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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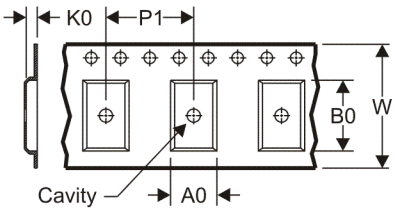
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TAPE AND REEL INFORMATION

REEL DIMENSIONS

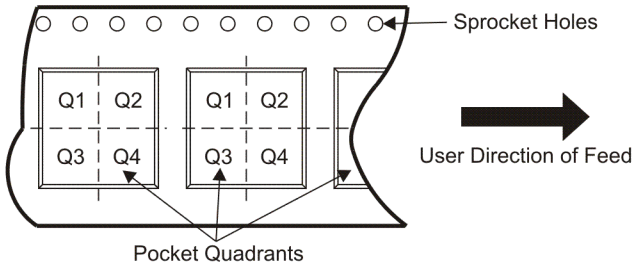


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

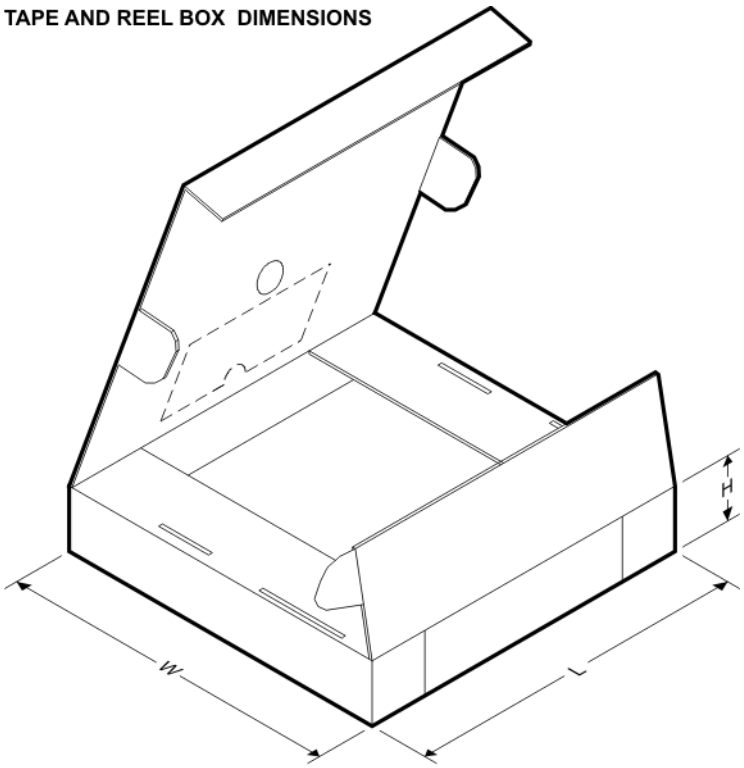
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT16853DGGR	TSSOP	DGG	56	2000	330.0	24.4	8.6	15.6	1.8	12.0	24.0	Q1
SN74ABT16853DLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT16853DGGR	TSSOP	DGG	56	2000	346.0	346.0	41.0
SN74ABT16853DLR	SSOP	DL	56	1000	346.0	346.0	49.0

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